Application title: Methods for Electroplating Large Copper Interconnects
Application No. 09/895,678

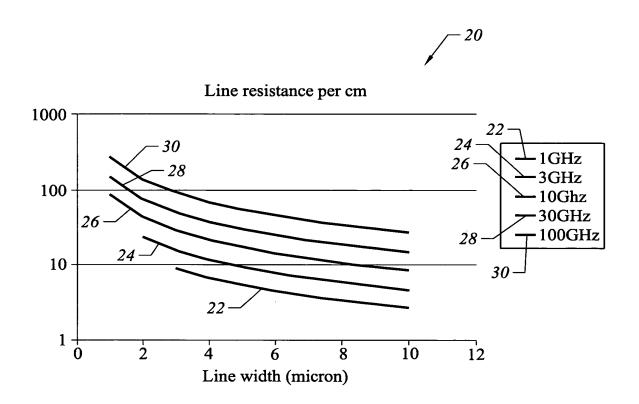


FIG. 1



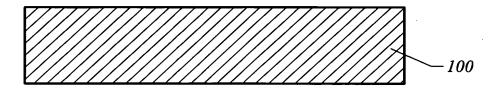


FIG. 2

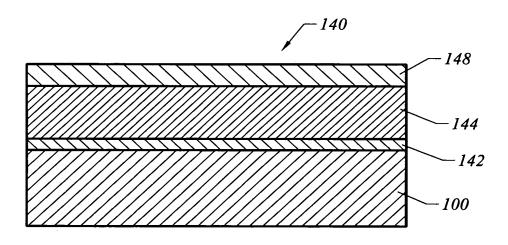


FIG. 3



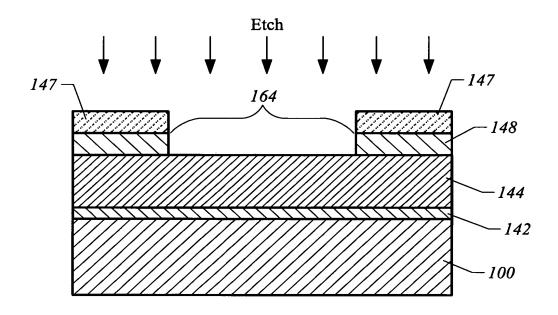


FIG. 4

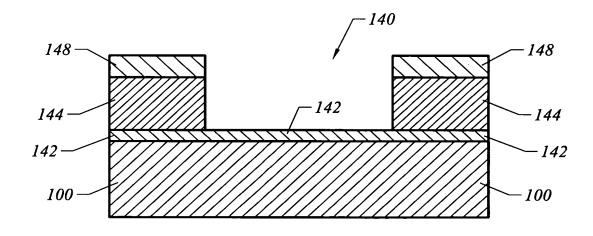


FIG. 5



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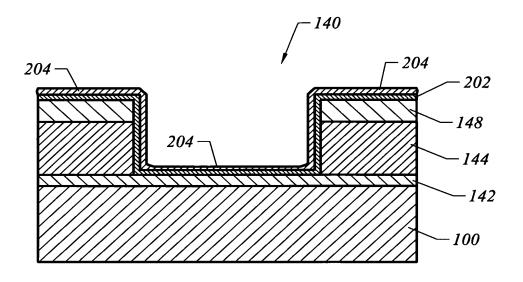


FIG. 6

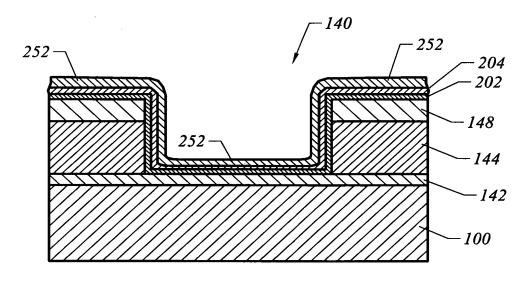


FIG. 7



Application title: Methods for Electroplating Large Copper Interconnects Application No. 09/895,678

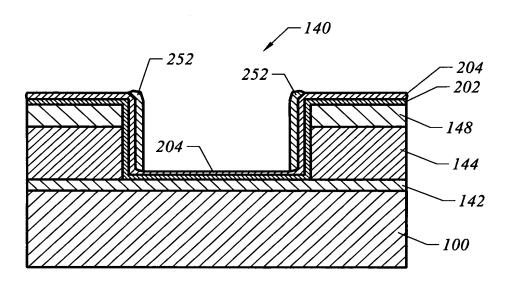


FIG. 8

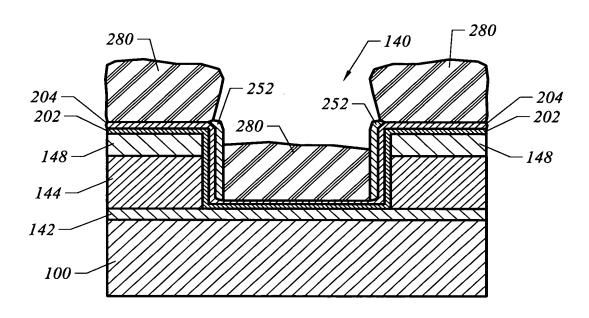


FIG. 9



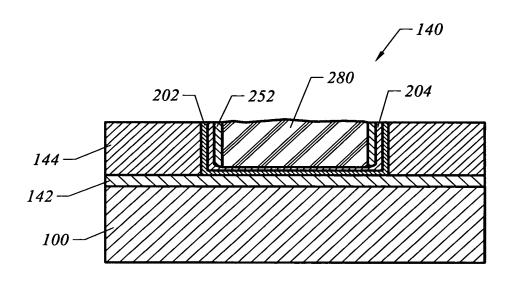


FIG. 10

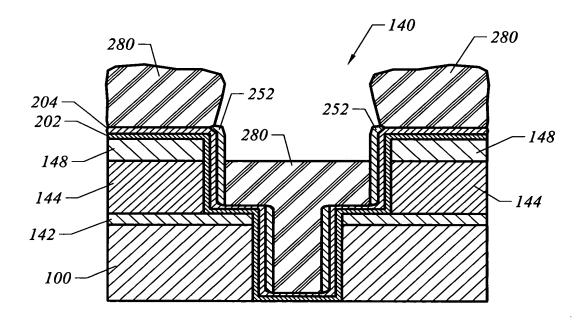


FIG. 11



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Application No. 09/895,678
Applicant: John Stephen Drewery
Filing Date: June 29, 2001

